

## AMENDMENTS TO THE CLAIMS

Claims 1-17 (Cancelled).

18. (Currently Amended) A multi-layer board comprising:

a ceramic layer having a first side and a second side opposite said first side, said ceramic layer having a dielectric constant;

an impedance element on said ceramic layer, said impedance element comprising a patterned inductor;

a first resin layer on said first side of said ceramic layer so as to contact said ceramic layer, said first resin layer having a dielectric constant lower than said dielectric constant of said ceramic layer, and having a first side facing said ceramic layer and a second side opposite said first side;

a second resin layer on said second side of said ceramic layer so as to contact said ceramic layer;

a third resin layer on said first resin layer so as to contact said first resin layer; ~~and~~

a strip line between said first resin layer and said third resin layer; and

a ground pattern on said second side of said first resin layer, said ground pattern and said patterned inductor being arranged such that no portion of said ground pattern is located on said second side of said first resin layer opposite a portion of said first side of said first resin layer facing said patterned inductor.

19. (Previously Presented) The multi-layer board of claim 18, further comprising an electronic component mounted on said first resin layer.

Claim 20 (Cancelled).

21. (Previously Presented) The multi-layer board of claim 18, further comprising a strip line on said third resin layer.

22. (Previously Presented) The multi-layer board of claim 18, further comprising an electronic component mounted on said third resin layer.

23. (Previously Presented) The multi-layer board of claim 18, further comprising a fourth resin layer on said third resin layer.

Claim 24 (Cancelled).

25. (Currently Amended) The multi-layer board of claim ~~24~~ 18, wherein said patterned inductor comprises a laser-trimmed patterned inductor.

Claims 26 and 27 (Cancelled).

28. (Previously Presented) The multi-layer board of claim 18, wherein said impedance element comprises a resistor.

29. (Previously Presented) The multi-layer board of claim 28, wherein said resistor comprises a laser-trimmed resistor.

30. (Previously Presented) The multi-layer board of claim 18, wherein said impedance element comprises a first impedance element on said first side of said ceramic layer, further comprising a second impedance element on said second side of said ceramic layer.

Claim 31 (Cancelled).

32. (Currently Amended) A multi-layer board comprising:  
a ceramic layer having a first side and a second side opposite said first side;

an a first impedance element including a patterned inductor on said first side of said ceramic layer;

a second impedance element on said second side of said ceramic layer;

a resin layer over said first side of said ceramic layer, said resin layer having a first side facing said first side of said ceramic layer and having a second side opposite said first side of said resin layer; and

a ground pattern on said second side of said resin layer, said ground pattern and said patterned inductor being arranged such that no portion of said ground pattern is located on a portion of said second side of said resin layer opposite a portion of said first side of said resin layer facing said patterned inductor so as to increase a Q-factor of said patterned inductor.

33. (Previously Presented) The multi-layer board of claim 32, further comprising an electronic component mounted on said resin layer.

34. (Previously Presented) The multi-layer board of claim 32, wherein said resin layer comprises a first resin layer over said first side of said ceramic layer, further comprising a second resin layer over said second side of said ceramic layer.

35. (Previously Presented) The multi-layer board of claim 34, further comprising a strip line on said second resin layer.

36. (Previously Presented) The multi-layer board of claim 34, further comprising a third resin layer over said first resin layer.

37. (Previously Presented) The multi-layer board of claim 36, further comprising a strip line on said third resin layer.

38. (Previously Presented) The multi-layer board of claim 36, further comprising an electronic component mounted on said third resin layer.

39. (Previously Presented) The multi-layer board of claim 36, further comprising a fourth resin layer between said first resin layer and said third resin layer.

40. (Previously Presented) The multi-layer board of claim 36, further comprising:  
a polyimide film between said first resin layer and said third resin layer; and  
a capacitor on said polyimide film.

41. (Previously Presented) The multi-layer board of claim 32, wherein said patterned inductor comprises a laser-trimmed patterned inductor.

Claim 42 (Cancelled).

43. (Previously Presented) The multi-layer board of claim 32, further comprising a strip line on said resin layer.

44. (Previously Presented) The multi-layer board of claim 18, further comprising:  
a polyimide film between said first resin layer and said third resin layer; and  
a capacitor on said polyimide film.

45. (Previously Presented) The multi-layer board of claim 18, wherein said third resin layer has a dielectric constant lower than said dielectric constant of said ceramic layer.

Claim 46 (Cancelled).

47. (Previously Presented) The multi-layer board of claim 32, wherein said resin layer has a dielectric constant lower than a dielectric constant of said ceramic layer.

Claim 48 (Cancelled).

49. (Previously Presented) The multi-layer board of claim 32, wherein said patterned inductor is arranged between said ceramic layer and said first resin layer.

50. (Previously Presented) The multi-layer board of claim 32, wherein said patterned inductor is arranged on said first side of said ceramic layer so as to contact said ceramic layer.

51. (Previously Presented) The multi-layer board of claim 32, wherein said patterned inductor has a spiral shape.

52. (New) A multi-layer board comprising:

a ceramic layer having a first side and a second side opposite said first side, said ceramic layer having a dielectric constant;

a first impedance element on said first side of said ceramic layer;

a second impedance element on said second side of said ceramic layer;

a first resin layer on said first side of said ceramic layer so as to contact said ceramic layer, said first resin layer having a dielectric constant lower than said dielectric constant of said ceramic layer;

a second resin layer on said second side of said ceramic layer so as to contact said ceramic layer;

a third resin layer on said first resin layer so as to contact said first resin layer; and

a strip line between said first resin layer and said third resin layer.

53. (New) The multi-layer board of claim 52, further comprising an electronic component mounted on said first resin layer.

54. (New) The multi-layer board of claim 52, further comprising a strip line on said third resin layer.

55. (New) The multi-layer board of claim 52, further comprising an electronic component mounted on said third resin layer.

56. (New) The multi-layer board of claim 52, further comprising a fourth resin layer on said third resin layer.

57. (New) The multi-layer board of claim 52, wherein said first impedance element comprises a resistor.

58. (New) The multi-layer board of claim 57, wherein said resistor comprises a laser-trimmed resistor.